Special Issue

Plasma-Based Surface Engineering

Message from the Guest Editors

Surface engineering is important for many applications, such as superhydrophobicity/superamphiphobicity, selfcleaning, anti-fogging, anti-icing, and antibacterial action. Engineering of such surfaces requires structuring at the micro and nano-scale or coatings with micro and/or nano-features and surface energy control. Plasma processing is already used for various surface treatments, yet new functionalities, which impose new requirements for surface engineering, are sought. In this Special Issue, we aim to collect all the recent achievements in plasma fabricated surfaces and their applications. We also aim to address durability and other performance issues, as well as modeling and design issues, towards a new generation of plasmabased functional surfaces. Additionally, we want to present the perspectives and challenges in the field. Contributions are expected to expand the field of application for the plasma-based surfaces.

Guest Editors

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Deadline for manuscript submissions

closed (30 April 2018)



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